

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1 through 7 (Cancelled without prejudice).

Claim 8 (Currently amended): A probe card structure comprising:

a probe section having an insulated circuit board,
a probe of silicon material formed on said insulated
circuit board for contacting a pad of a device to be
measured, and a conductive wiring in electrical
communication with said probe and disposed on said
insulated circuit board;

a supporting structure for supporting said probe
section;

a fixing structure for fixing a plurality of said
supporting structures together;

a printed circuit having a conductive wiring connected to said fixing structure, said printed circuit being electrically connected to a measurement device for transmitting a measurement signal to said device being measured;

a wiring connection for electrically connecting said conductive wiring of said probe and said conductive wiring in communication with said printed circuit, wherein said conductive wiring of said probe section and said conductive wiring of said printed circuit are electrically connected by a sub printed circuit, said sub printed circuit being selected from the group consisting of a flexible printed circuit, a rigid printed circuit board, and any combinations thereof; The probe card structure of claim 3, further comprising and

a contact pad of said sub printed circuit and a contact pad of said insulated circuit board being electrically connected by perpendicular conductor of silicon rubber material for conducting electricity between a top surface and a bottom surface through a plurality of vertically embedded metallic wires having a diameter of $35\mu\text{m}$ or less, wherein said plurality of vertically embedded metallic wires being are positioned in an array of a 0.07 through 0.45mm matrix.

Serial No.: 10/633,022
Group Art Unit No.: 2829

Claims 9 through 13 (Cancelled without prejudice).